

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph bridging pages 78-79, beginning with line 28, with the following amended paragraph:

The process shown in Fig. 2(a) to (e) is a process for establishing an electrical connection between two or more conductor layers 1006a, 1006b (2 layers in the drawing) which partly comprises piercing openings in the conductor layer 1006a by etching, forming openings for via holes 1007 within said opening between 1006a and 1006b by laser or other means (Fig. 2(b)) (Fig. 2(c)), forming a thin electroless plated metal layer 1008 within said openings 1007 (Fig. 2(e)) (Fig. 2(d)) and forming a thick-electroless plated electroplated metal layer 1009 (Fig. 2(d)) (Fig. 2(e)) to provide via holes 1010.